

[Title of Invention] DICING SHEET, METHOD FOR PRODUCING DICING SHEET, AND METHOD FOR PRODUCING MOLD CHIPS

[Name of Document] Abstract

A dicing sheet comprising a base film and a pressure sensitive adhesive layer laminated on at least one surface of the base film, the pressure sensitive adhesive layer being formed of a pressure sensitive adhesive composition that contains an acrylic-based polymer (A) having an energy ray polymerizable group and a reactive functional group and an isocyanate-based crosslinker (B) capable of a crosslinking reaction with the reactive functional group, the acrylic-based polymer (A) being obtained by a reaction between an acrylic-based polymer (A1) having the reactive functional group and an isocyanate-based compound (A2) having the energy ray polymerizable group under presence of an organometallic catalyst (C) that contains at least one of titanium and zirconium, the pressure sensitive adhesive layer having a storage elastic modulus at 23°C of 50 kPa or more and 80 kPa or less before irradiation with energy rays and 5.0 MPa or more after irradiation with energy rays, the pressure sensitive adhesive layer having a thickness of less than 20 μm , the pressure sensitive adhesive layer having a surface of which an energy amount before irradiation with energy rays is 0.1 mJ/5 mm ϕ or more and 0.8 mJ/5 mm ϕ or less, the energy amount being measured using probe tack under a condition in which a peeling speed is changed to 1 mm/minute in a method as described in JIS Z0237:1991. According to the dicing sheet, the possibility of occurrence of troubles is reduced in any of the dicing step, expanding step, and pickup step. The dicing sheet can be used to produce high-quality mold chips at low cost.